ASSOCIATION CONNECTIN	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This d level p	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1					Form Type * Distribute	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					ials and Mfg Information			
Supplier Inforn	nation													
Company name*			Company unique ID			Un	Unique ID Authority				Response Date*			
onsemi										2023-06-08				
Contact Name		Title - Contact			Ph	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards	Product Enviro Compliance			N.	NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			Ph	Phone - Representative*				Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance			N.	NA				Product-Env-Stewards@onsemi.com			
Request	er Item Number	Mfr Item Number Mfr Item Name NCP3235MNTXG High Current Syn		Mfr Item Name		Е	Effective Date	Version	1	Manufacturing Site		Weight*	UOM	Unit Type
				chronous Buck Conve	rter 20	2023-06-08		PH1		114.9	mg	Each		
Ianufacturing	Proccess Informatio	n				·								
Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020 MS		J-STD-020 MSL Ratin	g	Peak Proce	k Process Body Temperatu		re Max Time at Peak	Tempera	ture Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		C	CU Alloy 3			260 C 30		seconds 3						
omments														
TTENTION: MS	L 3 Rated item requires B	ake and D	ry Pack (afte	r electrical test)										
or more informati	on regarding material cor	nposition j	please refer t	o page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its products a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	15.66	mg	Supplier	Zinc (Zn)	7440-66-6		0.0188	mg
			Supplier	Iron (Fe)	7439-89-6		0.368	mg
			Supplier	Copper (Cu)	7440-50-8		15.2685	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0047	mg
Die	4.6	mg	Supplier	Silicon (Si)	7440-21-3		4.6	mg
Die Attach Solder	1.72	mg	Supplier	Silver (Ag)	7440-22-4		0.043	mg
			A	Lead (Pb)	7439-92-1	7a	1.591	mg
			Supplier	Tin (Sn)	7440-31-5		0.086	mg
Lead Frame	40.03	mg	Supplier	Silver (Ag)	7440-22-4		0.4003	mg
			Supplier	Tin (Sn)	7440-31-5		0.1001	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0881	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1001	mg
			Supplier	Copper (Cu)	7440-50-8		39.3415	mg
Mold Compound-Black	51.07	mg		Epoxy resin	proprietary data		2.4003	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		5.107	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0511	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		41.1114	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.4003	mg
Plating	1.49	mg	Supplier	Tin (Sn)	7440-31-5		1.49	mg
Wire Bond	0.33	mg	Supplier	Palladium (Pd)	7440-05-3		0.0033	mg
			Supplier	Copper (Cu)	7440-50-8		0.3267	mg